

EEPROM 1M 5V SDP - 150NS 32883C

Manufacturers	<a href="#">Microchip Technology, Inc</a>
Package/Case	CERDIP-32
Product Type	Memory
RoHS	
Lifecycle	



Images are for reference only

Please submit RFQ for AT28C010-15DM/883 or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

## General Description

The Microchip AT28C010 is a high-performance 1-megabit Parallel EEPROM available in both Industrial and Military temperatures, offering access times to 120ns with power dissipation of 220mW (440mW military). Deselected, CMOS standby current is less than 200µA (300µA military). Access like static RAM for the read or write cycle without external components; a 128byte page register to allow writing of up to 128bytes simultaneously. Features an internal Error Correction Circuit for extended endurance and improved data retention. Optional Software Data Protection mechanism guards against inadvertent writes; and an extra 128 bytes of EEPROM enables device identification or tracking.

The AT28C010 is also available DUAL MARKED where applicable with the appropriate Standard Military Drawing Number - 5962-382670xxMxx. See the separate MIL datasheet for exact availability.

## Features

128 Kbits x 8 (1 megabit)

5V ± 10% Supply

Parallel Interface

120ns access time

Self-Timed Erase and Write Cycles (10 ms max)

Page Write and Byte Write

Data Polling for end of write detection

Low Power Consumption

Read / Write current 40 mA (Max)

Standby current TTL 2 mA (Max), CMOS 200 µA (Max)

Write-Protection

Hardware Data Protection

Software Data Protection

High-endurance Option 100,000 erase/write cycles

Data retention > 10 years

Temperature Ranges

Standard Temperature Range: -40°C to 85°C

Military Temperature Range: -55°C to 125°C

Available in Green (Pb/Halide-free) Packaging

32-lead, Plastic J-leaded Chip Carrier (PLCC)

32-lead, Plastic Thin Small Outline Package (TSOP)

Available in dual marked (5962-382670xxx) CERAMIC Hermetic Packaging

32-Lead, 0.600" Wide, Non-Windowed, Ceramic Dual Inline (Cerdip)

32-Lead, Non-Windowed, Ceramic Bottom-Brazed Flat Package (Flatpack)

32-Pad, Non-windowed, Ceramic, Leadless Chip Carrier (LCC)



## Related Products



### [AT27C010-45JU](#)

Microchip Technology, Inc  
PLCC-32



### [AT24CM02-SSHD-B](#)

Microchip Technology, Inc  
SOIC-8



### [24LC32AT-I/SN](#)

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SOIC-8



### [AT24CM02-SSHM-B](#)

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### [AT24C512C-SSHM-T](#)

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### [AT24C04D-MAHM-T](#)

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[AT28BV256-20SU](#)

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[AT28C010E-12DM/883](#)

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